

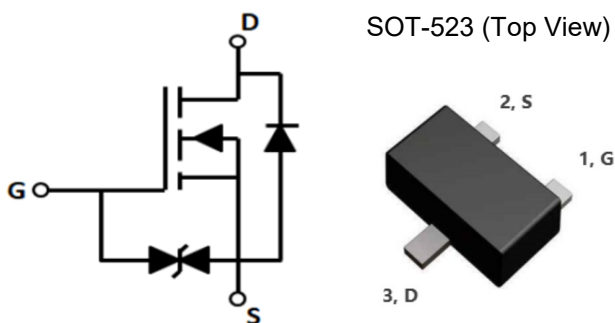
## Description

CM3134BT is the N-Channel enhancement mode power field effect transistors with high cell density, trench technology. This high density process and design have been optimized switching performance and especially tailored to minimize on-state resistance.

## Features

- $V_{DS}$ : 20V
- $I_D$ : 0.75A
- $R_{DS(on)}$  (@ $V_{GS}=4.5V$ ) : < 330m $\Omega$
- $R_{DS(on)}$  (@ $V_{GS}=2.5V$ ) : < 480m $\Omega$
- $R_{DS(on)}$  (@ $V_{GS}=1.8V$ ) : < 800m $\Omega$
- High density cell design for extremely low  $R_{DS(on)}$
- Excellent on-resistance and DC current capability

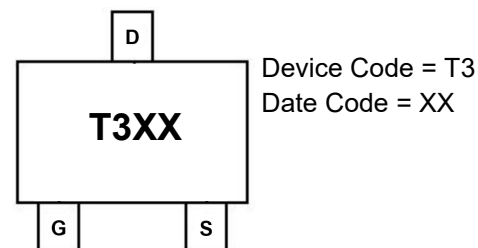
## Equivalent Circuit and Pin Configuration



## Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Portable Instrumentation
- Load switch

## Marking Information



## Ordering Information

Part Number	Packaging	Reel Size
CM3134BT	3000/Tape & Reel	7 inch

## Absolute Maximum Ratings (TA=25 °C unless otherwise noted)

Parameter		Symbol	Maximum	Unit
Drain-source Voltage		$V_{DS}$	20	V
Gate-source Voltage		$V_{GS}$	$\pm 10$	V
Continuous Drain Current	$T_A=25^\circ\text{C}$ , Steady State	$I_D$	0.75	A
	$T_A=75^\circ\text{C}$ , Steady State		0.58	A
Pulsed Drain Current <sup>(1)</sup>		$I_{DM}$	3.0	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$ <sup>(2)</sup> @Steady State		PD	310	mW
Thermal Resistance Junction-to-Ambient <sup>(2)</sup> @Steady State		$R_{\theta JA}$	400	$^\circ\text{C/W}$
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics (T<sub>J</sub>=25 °C unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>C</sub> =25°C			1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V			±10	uA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.35		1.1	V
Static Drain-Source on-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.5A		220	330	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =0.3A		300	480	
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =0.25A		450	800	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =0.75A, V <sub>GS</sub> =0V			1.2	V
Maximum Body-Diode Continuous Current	I <sub>S</sub>				0.75	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, f=1MHz		24		pF
Output Capacitance	C <sub>oss</sub>			7.5		
Reverse Transfer Capacitance	C <sub>rss</sub>			3		
<b>Switching Parameters</b>						
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =4.5V, V <sub>DD</sub> =10V, I <sub>D</sub> =0.5A, R <sub>GEN</sub> =10Ω		6.7		ns
Turn-on Rise Time	t <sub>r</sub>			4.8		
Turn-off Delay Time	t <sub>D(off)</sub>			17.3		
Turn-off Fall Time	t <sub>f</sub>			7.4		

Noted: (1) Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

(2) Surface mounted on FR4 board using the minimum recommended pad size.

**Typical Performance Characteristics**

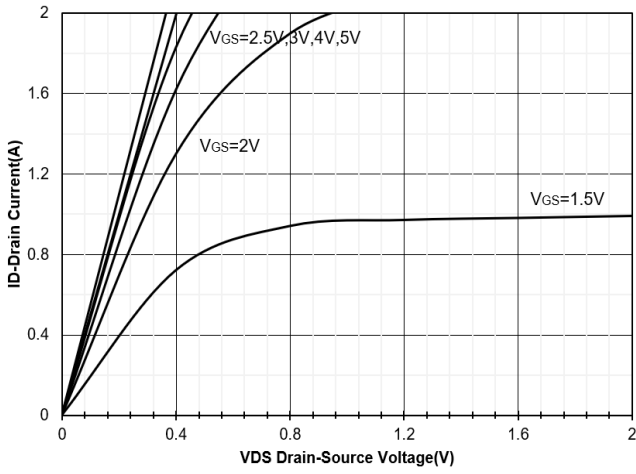


Figure 1. Output Characteristics

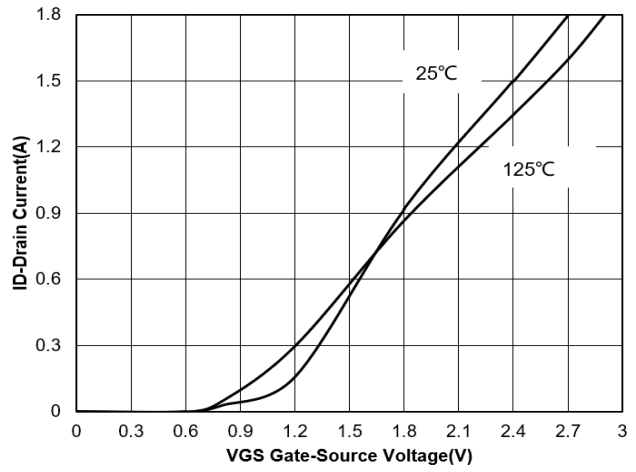


Figure 2. Transfer Characteristics

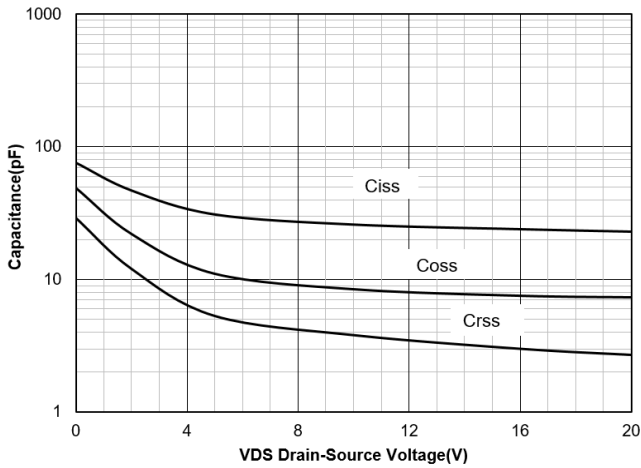


Figure 3. Capacitance Characteristics

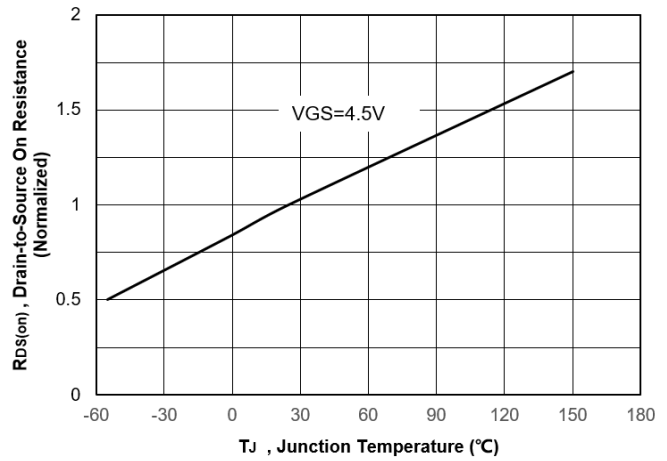


Figure 4. Normalized On-Resistance Vs. Temperature

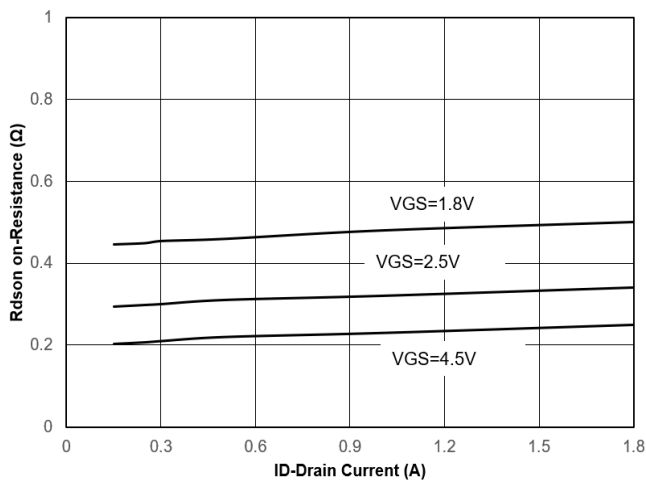


Figure 5. Drain-Source on Resistance

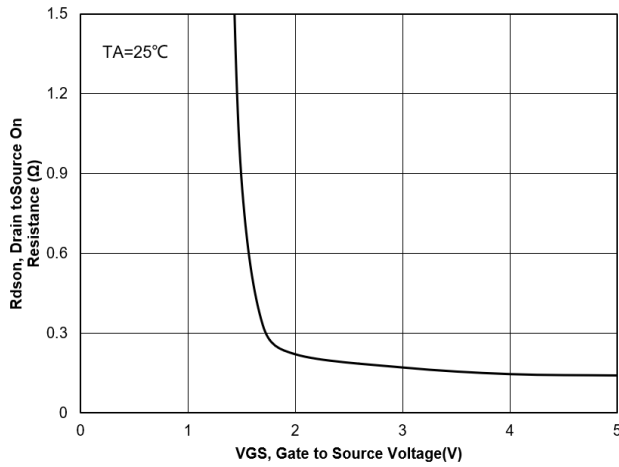


Figure 6. Typical Drain to Source ON Resistance VS Gate Voltage and Drain Current

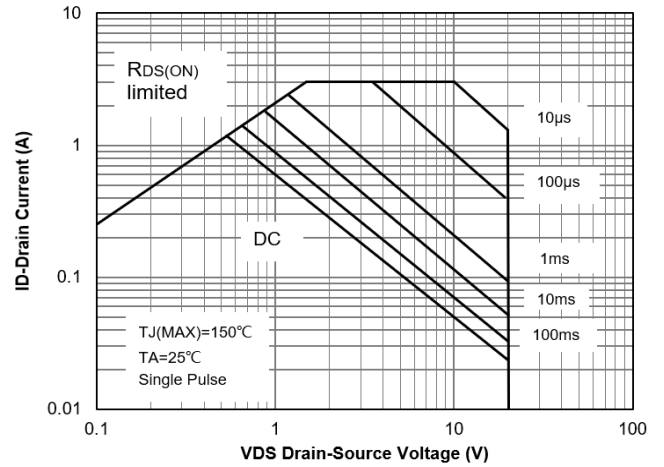


Figure 7. Safe Operation Area

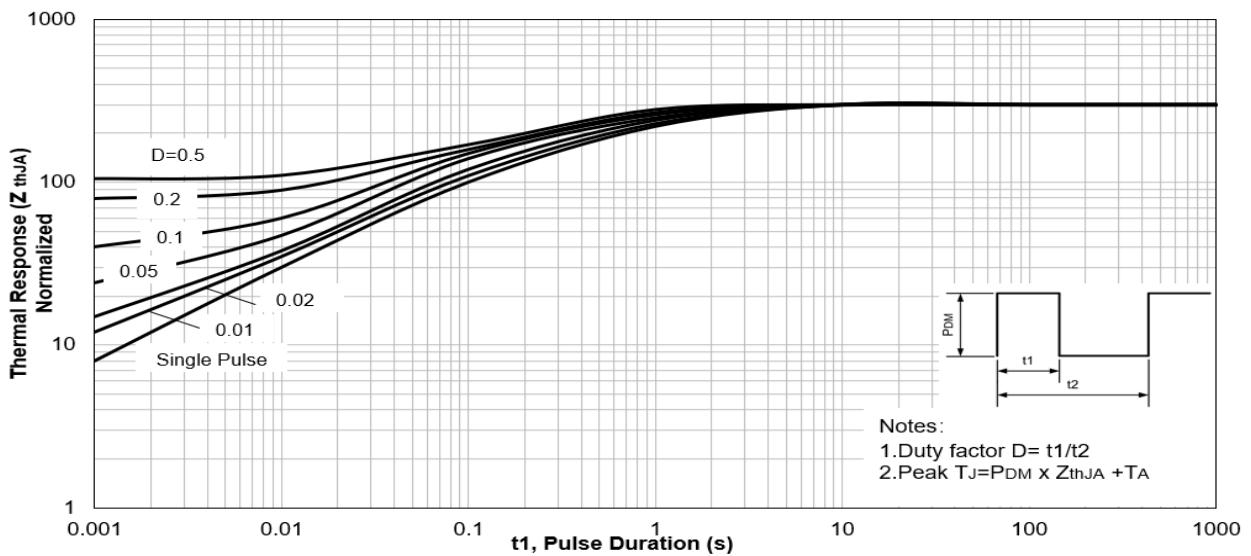


Figure 8. Maximum Effective Transient Thermal Impedance ,Junction-to-Ambient

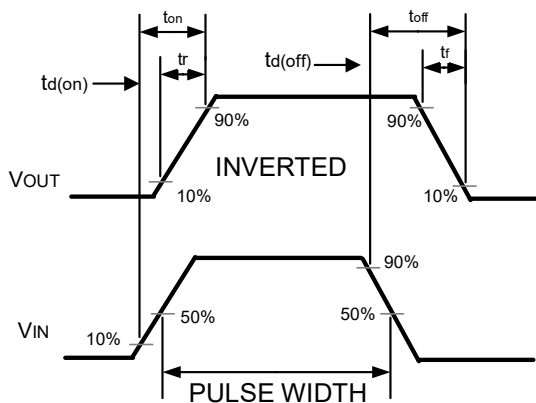
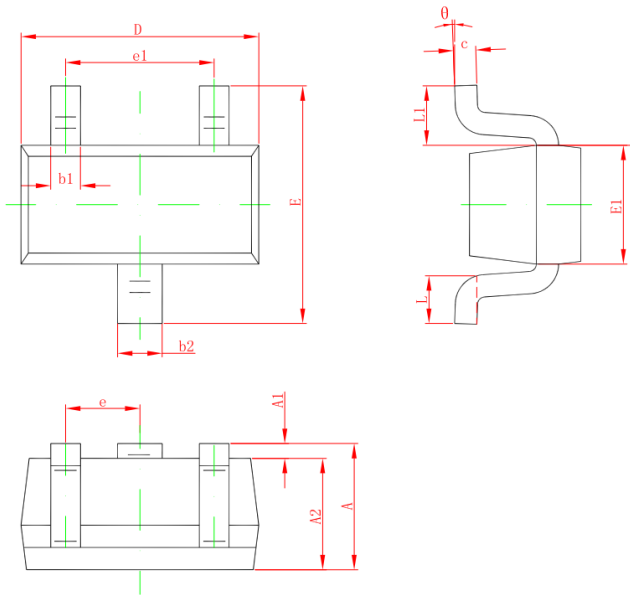


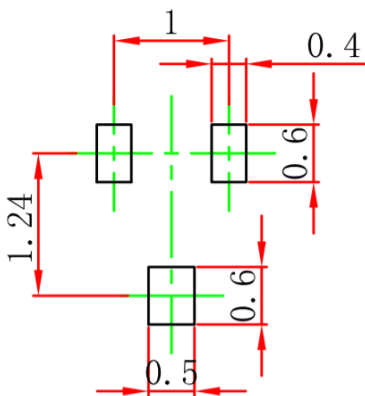
Figure 9. Switching wave

### SOT-523 Package Outline Drawing



Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b1	0.150	0.250	0.006	0.010
b2	0.250	0.350	0.010	0.014
c	0.100	0.200	0.004	0.008
D	1.500	1.700	0.059	0.067
E	1.450	1.750	0.057	0.069
E1	0.700	0.900	0.028	0.035
e	0.500 TYP.		0.020 TYP.	
e1	0.900	1.100	0.035	0.043
L	0.400 REF.		0.016 REF.	
L1	0.260	0.460	0.010	0.018
theta	0°	8°	0°	8°

### Suggested Land Pattern



### Contact Information

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